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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

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Details

Product Status	Obsolete
Core Processor	80515
Core Size	8-Bit
Speed	24MHz
Connectivity	I ² C, SmartCard, UART/USART
Peripherals	LED, POR, WDT
Number of I/O	8
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 6.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VFQFN Exposed Pad
Supplier Device Package	44-QFN (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/analog-devices/73s1210f-44im-f

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Miscellaneous Control Register 1 (MISCtl1): 0xFFFF2 ← 0x10**Table 16: The MISCtl1 Register**

MSB	-	-	FRPEN	FLSH66	-	-	-	-	LSB

Bit	Symbol	Function
MISCtl1.7	–	
MISCtl1.6	–	
MISCtl1.5	FRPEN	Flash Read Pulse enable (low). If FRPEN = 1, the Flash Read signal is passed through with no change. When FRPEN = 0 a one-shot circuit that shortens the Flash Read signal is enabled to save power. The Flash Read pulse will shorten to 40 or 66ns (approximate based on the setting of the FLSH66 bit) in duration, regardless of the MPU clock rate. For MPU clock frequencies greater than 10MHz, this bit should be set high.
MISCtl1.4	FLSH66	When high, creates a 66ns Flash read pulse, otherwise creates a 40ns read pulse when FRPEN is set.
MISCtl1.3	–	
MISCtl1.2	–	
MISCtl1.1	–	
MISCtl1.0	–	

Master Clock Control Register (MCLKCtl): 0x8F ← 0x0A**Table 17: The MCLKCtl Register**

MSB	HSOEN	KBEN	SCEN	–	–	MCT.2	MCT.1	MCT.0	LSB

Bit	Symbol	Function
MCLKCtl.7	HSOEN*	High-speed oscillator enable. When set = 1, disables the high-speed crystal oscillator and VCO/PLL system. This bit is not changed when the PWRDN bit is set but the oscillator/VCO/PLL is disabled.
MCLKCtl.6	KBEN	1 = Disable the keypad logic clock. This bit is not changed in PWRDN mode but the function is disabled.
MCLKCtl.5	SCEN	1 = Disable the smart card logic clock. This bit is not changed in PWRDN mode but the function is disabled. Interrupt logic for card insertion/removal remains operable even with smart card clock disabled.
MCLKCtl.4	–	
MCLKCtl.3	–	
MCLKCtl.2	MCT.2	This value determines the ratio of the VCO frequency (MCLK) to the high-speed crystal oscillator frequency such that:
MCLKCtl.1	MCT.1	MCLK = (MCount*2 + 4)*Fxtal. The default value is MCount = 2h such that MCLK = (2*2 + 4)*12.00MHz = 96MHz.
MCLKCtl.0	MCT.0	

*Note: The HSOEN bit should never be set under normal circumstances. Power down control should only be initiated via use of the PWRDN bit in [MISCtl0](#).

Power Control Register 0 (PCON): 0x87 ← 0x00

The SMOD bit used for the baud rate generator is set up via this register.

Table 18: The PCON Register

Bit	Symbol	Function
PCON.7	SMOD	If SMOD = 1, the baud rate is doubled.
PCON.6	–	
PCON.5	–	
PCON.4	–	
PCON.3	GF1	General purpose flag 1.
PCON.2	GF0	General purpose flag 1.
PCON.1	STOP	Sets CPU to Stop mode.
PCON.0	IDLE	Sets CPU to Idle mode.

- Mode 3**

The only difference between Mode 2 and Mode 3 is that in Mode 3 either internal baud rate generator or timer 1 can be used to specify baud rate.

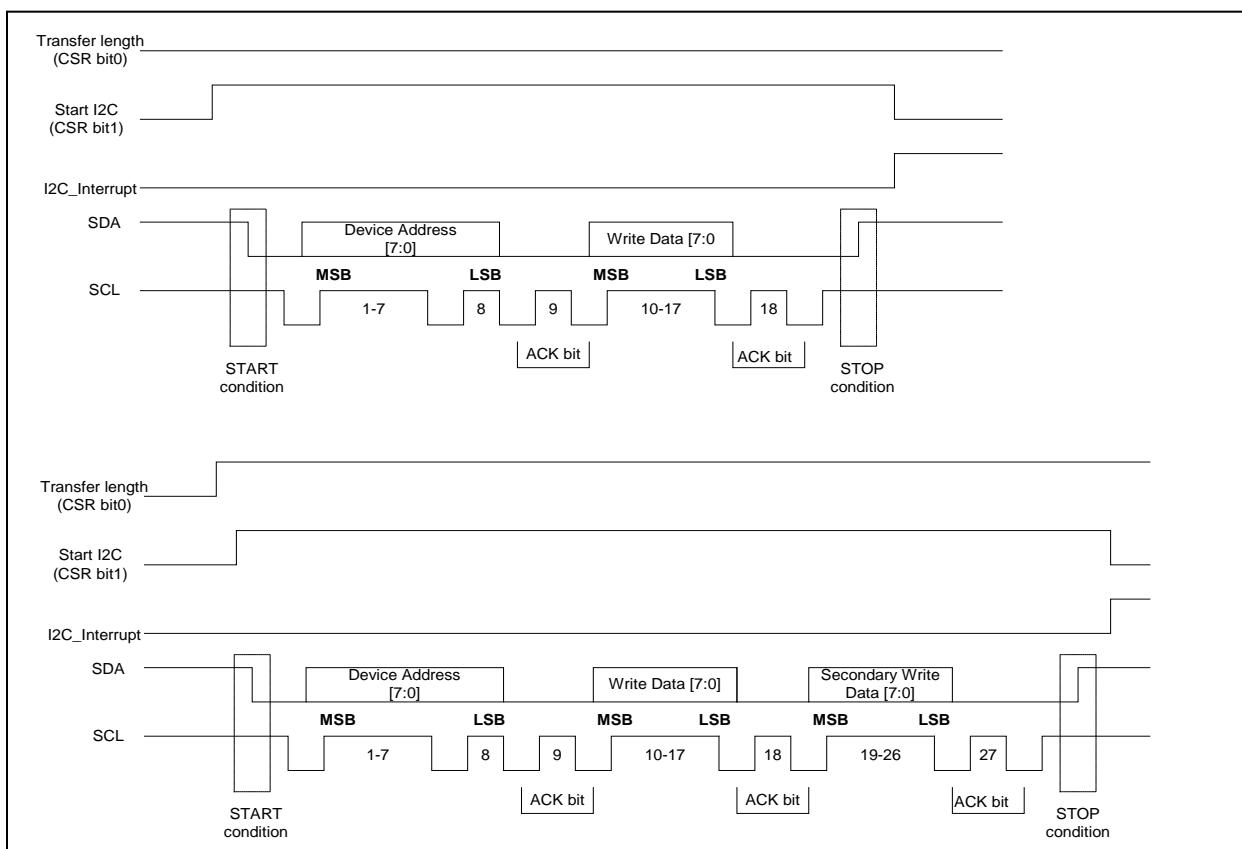
The **S0BUF** register is used to read/write data to/from the serial 0 interface.

Serial Interface 0 Control Register (S0CON): 0x9B ← 0x00

Transmit and receive data are transferred via this register.

Table 38: The S0CON Register

Bit	Symbol	Function							
		MSB			LSB				
		SM0	SM1	SM20	REN0	TB80	RB80	TI0	RI0
S0CON.7	SM0	These two bits set the UART0 mode:							
		Mode	Description	SM0	SM1				
		0	N/A	0	0				
		1	8-bit UART	0	1				
S0CON.6	SM1	2	9-bit UART	1	0				
		3	9-bit UART	1	1				
S0CON.5	SM20	Enables the inter-processor communication feature.							
S0CON.4	REN0	If set, enables serial reception. Cleared by software to disable reception.							
S0CON.3	TB80	The 9th transmitted data bit in Modes 2 and 3. Set or cleared by the MPU, depending on the function it performs (parity check, multiprocessor communication etc.).							
S0CON.2	RB80	In Modes 2 and 3 it is the 9th data bit received. In Mode 1, if SM20 is 0, RB80 is the stop bit. In Mode 0 this bit is not used. Must be cleared by software.							
S0CON.1	TI0	Transmit interrupt flag, set by hardware after completion of a serial transfer. Must be cleared by software.							
S0CON.0	RI0	Receive interrupt flag, set by hardware after completion of a serial reception. Must be cleared by software.							

Figure 10: I²C Write Mode Operation

1.7.12.2 I²C Read Sequence

To read data on the I²C Master Bus from a slave device, the 80515 has to program the following registers in this sequence:

1. Write slave device address to Device Address register ([DAR](#)). The data contains 7 bits device address and 1 bit of op-code. The op-code bit should be written with a 1.
2. Write control data to Control and Status register. Write a 1 to bit 1 to start I²C Master Bus. Also write a 1 to bit 0 if the Secondary Read Data register ([SRDR](#)) is to be captured from the I²C Slave device.
3. Wait for I²C interrupt to be asserted. It indicates that the read operation on the I²C bus is done. Refer to information about the [INT6Ctl](#), [IEN1](#) and [IRCON](#) registers for masking and flag operation.
4. Read data from the Read Data register ([RDR](#)).
5. Read data from Secondary Read Data register ([SRDR](#)) if bit 0 of Control and Status register ([CSR](#)) is written with a 1.

1.7.13 Keypad Interface

The 73S1210F supports a 30-button (6 rows x 5 columns) keypad (SPST Mechanical Contact Switches) interface using 11 dedicated I/O pins. Figure 12 shows a simplified block diagram of the keypad interface.

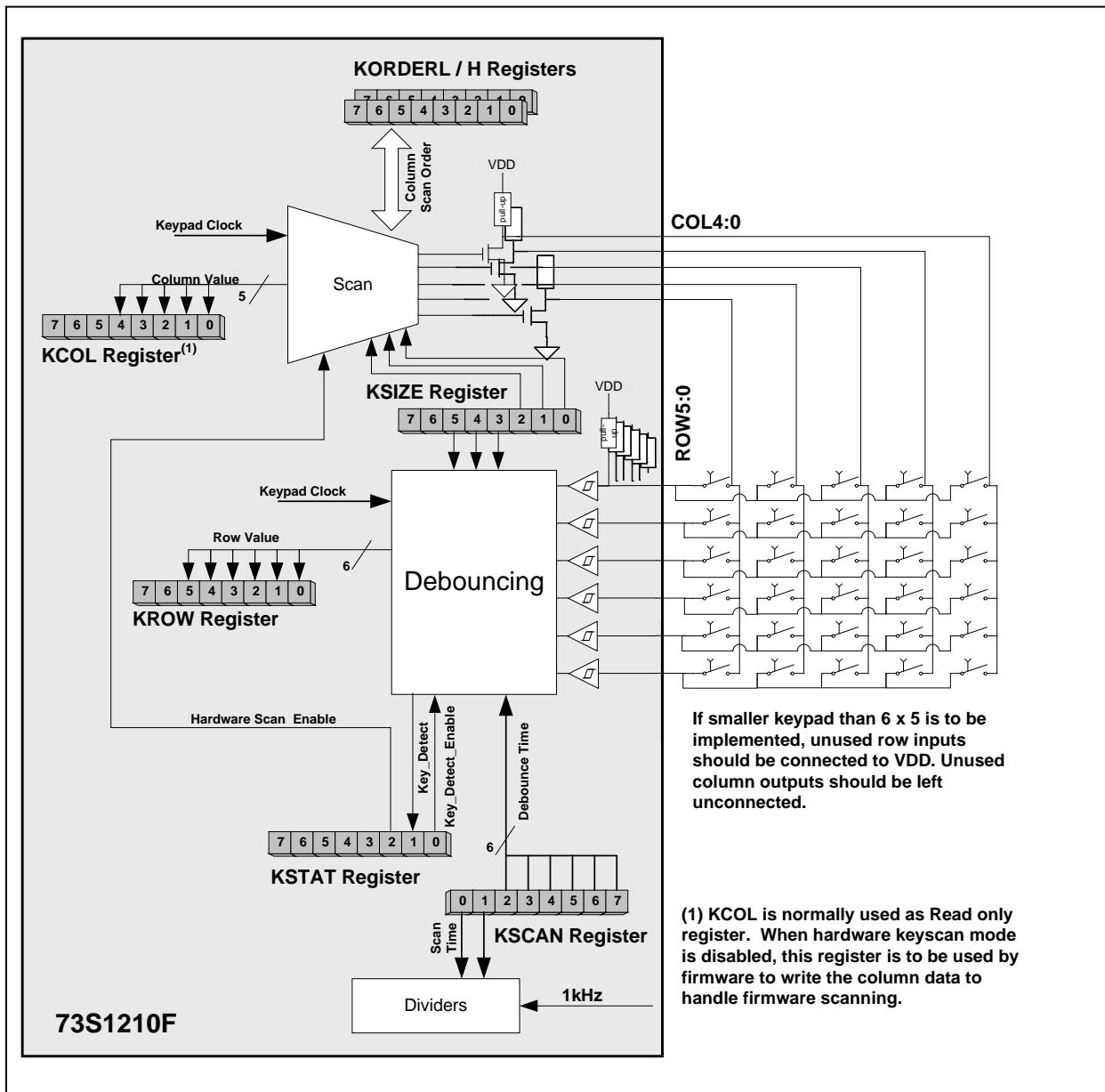


Figure 12: Simplified Keypad Block Diagram

There are five drive lines (outputs) corresponding to columns and 6 sense lines (inputs) corresponding to rows. Hysteresis and pull-ups are provided on all inputs (rows), which eliminate the need for external resistors in the keypad. Key scanning happens by asserting one of the 5 column lines low and looking for a low on a sense line indicating that a key is pressed (switch closed) at the intersection of the drive/sense (column/row) line in the keypad. Key detection is performed by hardware with an incorporated debounce timer. Debouncing time is adjustable through the **KSCAN** register. Internal hardware circuitry performs column scanning at an adjustable scanning rate and column scanning order through registers **KSCAN** and **KORDERL / KORDERH**. Key scanning is disabled at reset and must be enabled by firmware. When a valid key is detected, an interrupt is generated and the valid value of the pressed key is automatically

External Interrupt Control Register (INT5Ctl): 0xFF94 ← 0x00**Table 71: The INT5Ctl Register**

MSB							LSB
PDMUX	-	-	-	-	-	KPIEN	KPINT

Bit	Symbol	Function
INT5Ctl.7	PDMUX	Power down multiplexer control.
INT5Ctl.6	-	
INT5Ctl.5	-	
INT5Ctl.4	-	
INT5Ctl.3	-	
INT5Ctl.2	-	
INT5Ctl.1	KPIEN	Enables Keypad interrupt when set = 1.
INT5Ctl.0	KPINT	This bit indicates the Keypad logic has set Key_Detect bit and a key location may be read. Cleared on read of register.

1.7.14 Emulator Port

The emulator port, consisting of the pins E_RST, E_TCLK and E_RXTX, provides control of the MPU through an external in-circuit emulator. The E_TBUS[3:0] pins, together with the E_ISYNC/BRKRQ, add trace capability to the emulator. The emulator port is compatible with the ADM51 emulators manufactured by Signum Systems™.

The signals of the emulator port have weak pull-ups. Adding resistor footprints for signals E_RST, E_TCLK and E_RXTX on the PCB is recommended. If necessary, adding 10kΩ pull-up resistors on E_TCLK and E_RXTX and a 3kΩ on E_RST will help the emulator operate normally if a problem arises. If code trace capability is needed on this interface, 20pF capacitors (to ground) need to be added to allow the trace function capability to run properly. These capacitors should be attached to the TBUS0:3 and ISBR signals.

on a card insertion / removal to allow power saving modes. Card insertion / removal is generated from the respective card switch detection inputs (whose polarity is programmable).

The built-in ICC Interface has a linear regulator (V_{CC} generator) capable of driving 1.8, 3.0 and 5.0V smart cards in accordance with the ISO 7816-3 and EMV4.1 standards. This converter uses the V_P (5.5V nominal) input supply source. See the power supply management section above for more detail. Auxiliary I/O lines C4 and C8 are only provided for the built-in interface. If support for the auxiliary lines is necessary for the external smart card interface, they need to be handled manually through the USR GPIO pins. The external 73S8010x devices directly connect the I/O (SIO) and clock (SCLK) signals and control is handled via the I^2C interface.

Figure 15 shows how multiple 8010 devices can be connected to the 73S1210F.

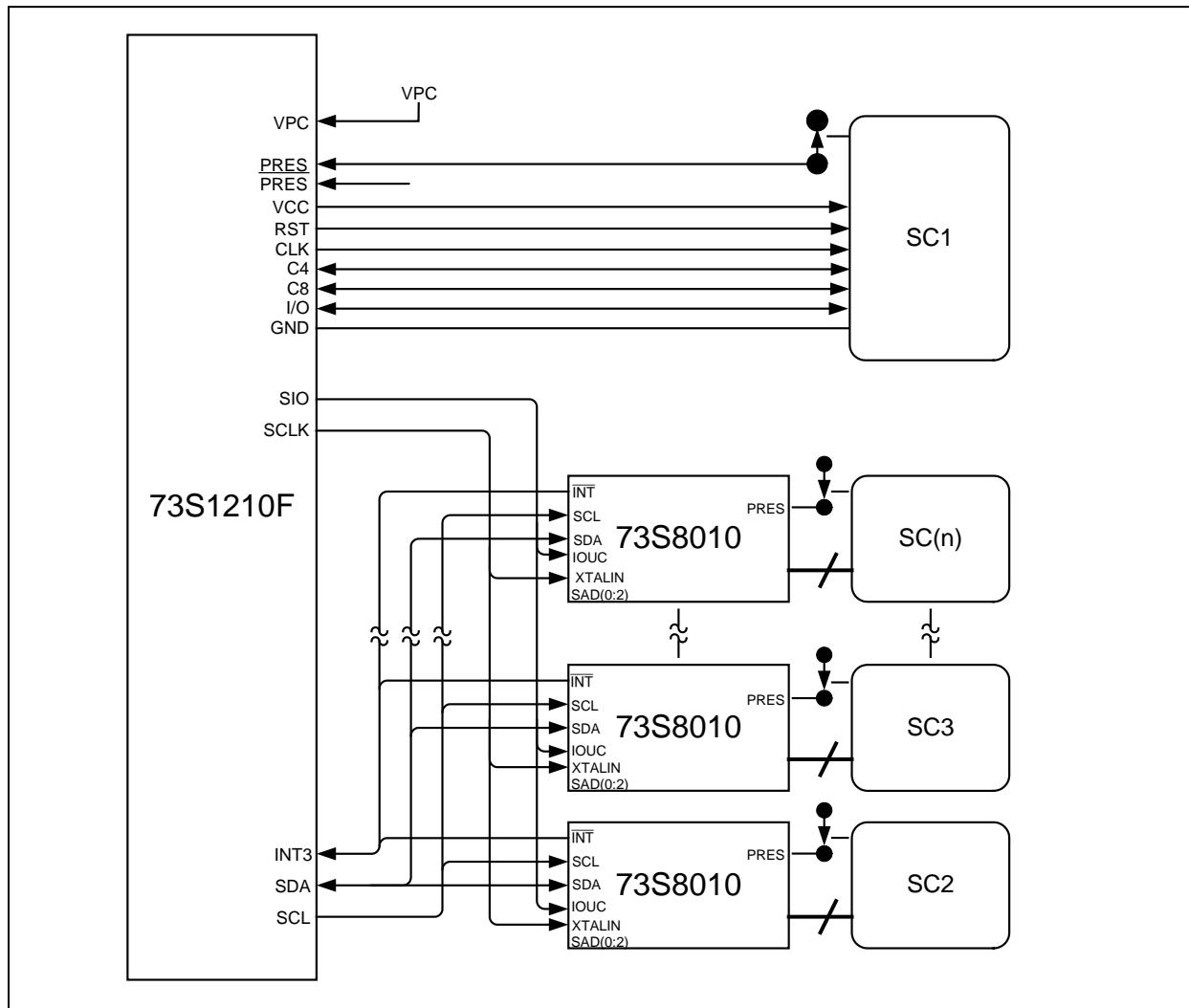


Figure 15: External Smart Card Interface Block Diagram

1.7.15.1 ISO 7816 UART

An embedded ISO 7816 (hardware) UART is provided to control communications between a smart card and the 73S1210F MPU. The UART can be shared between the one built-in ICC interface and the external ICC interface. Selection of the desired interface is made by register SCSel. Control of the external interface is handled by the I²C interface for any external 73S8010x device. The following is a list of features for the ISO 7816 UART:

- Two-byte FIFO for temporary data storage on both TX and Rx data.
- Parity checking in T=0. This feature can be enabled/disabled by firmware. Parity error reporting to firmware and Break generation to ICC can be controlled independently.
- Parity error generation for test purposes.
- Retransmission of last byte if ICC indicates T=0 parity error. This feature can be enabled/disabled by firmware.
- Deletion of last byte received if ICC indicates T=0 parity error. This feature can be enabled/disabled by firmware.
- CRC/LRC generation and checking. CRC/LRC is automatically inserted into T=1 data stream by the hardware. This feature can be enabled/disabled by firmware.
- Support baud rates: 115200, 57600, 38400, 28800, 19200, 14400, 9600 under firmware control (assuming 12MHz crystal) with various F/D settings.
- Firmware manages F/D. All F/D combinations are supported in which F/D is directly divisible by 31 or 32 (i.e. F/D is a multiple of either 31 or 32).
- Flexible ETU clock generation and control.
- Detection of convention (direct or indirect) character TS. This affects both polarity and order of bits in byte. Convention can be overridden by firmware.
- Supports WTX Timeout with an expanded Wait Time Counter (28 bits).
- A Bypass Mode is provided to bypass the hardware UART in order for the software to emulate the UART (for non-standard operating modes). In such a case, the I/O line value is reflected in SFR [SCCtl](#) or [SCECtl](#) respectively for the built-in or external interfaces. This mode is appropriate for some synchronous and non T=0 / T=1 cards.

The single integrated smart card UART is capable of supporting T=0 and T=1 cards in hardware therefore offloading the bit manipulation tasks from the firmware. The embedded firmware instructs the hardware which smart card it should communicate with at any point in time. Firmware reconfigures the UART as required when switching between smart cards. When the 73S1210F has transmitted a message with an expected response, the firmware should not switch the UART to another smart card until the first smart card has responded. If the smart card responds while another smart card is selected, that first smart card's response will be ignored.

1.7.15.2 Answer to Reset Processing

A card insertion event generates an interrupt to the firmware, which is then responsible for the configuration of the electrical interface, the UART and activation of the card. The activation sequencer goes through the power up sequence as defined in the ISO 7816-3 specification. An asynchronous activation timing diagram is shown in

Figure 16. After the card reset is de-asserted, the firmware instructs the hardware to look for a TS byte that begins the ATR response. If a response is not provided within the pre-programmed timeout period, an interrupt is generated and the firmware can then take appropriate action, including instructing the 73S1210F to begin a deactivation sequence. Once commanded, the deactivation sequencer goes through the power down sequence as defined in the ISO 7816-3 specification. If an ATR response is received, the hardware looks for a TS byte that determines direct/inverse convention. The hardware handles the indirect convention conversion such that the embedded firmware only receives direct convention. This feature can be disabled by firmware within [SByteCtl](#) register. Parity checking and break generation is performed on the TS byte unless disabled by firmware. If during the card session, a card removal, over-current or other error event is detected, the hardware will automatically perform the deactivation sequence and then generate an interrupt to the firmware. The firmware can then perform any other error handling required for proper system operation. Smart card RST, I/O and CLK, C4, C8 shall be low before the end of the deactivation sequence. Figure 17 shows the timing for a deactivation sequence.

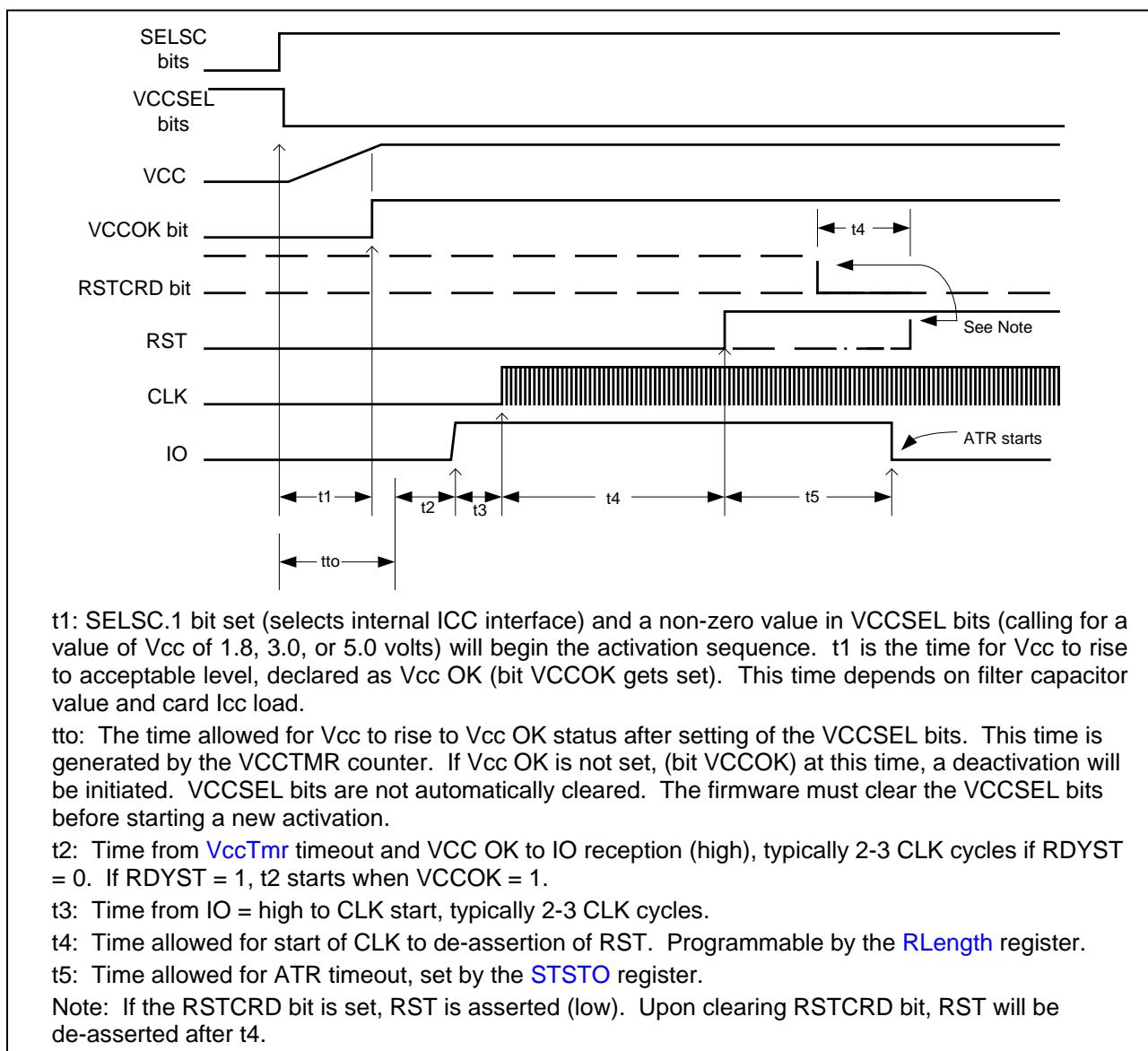
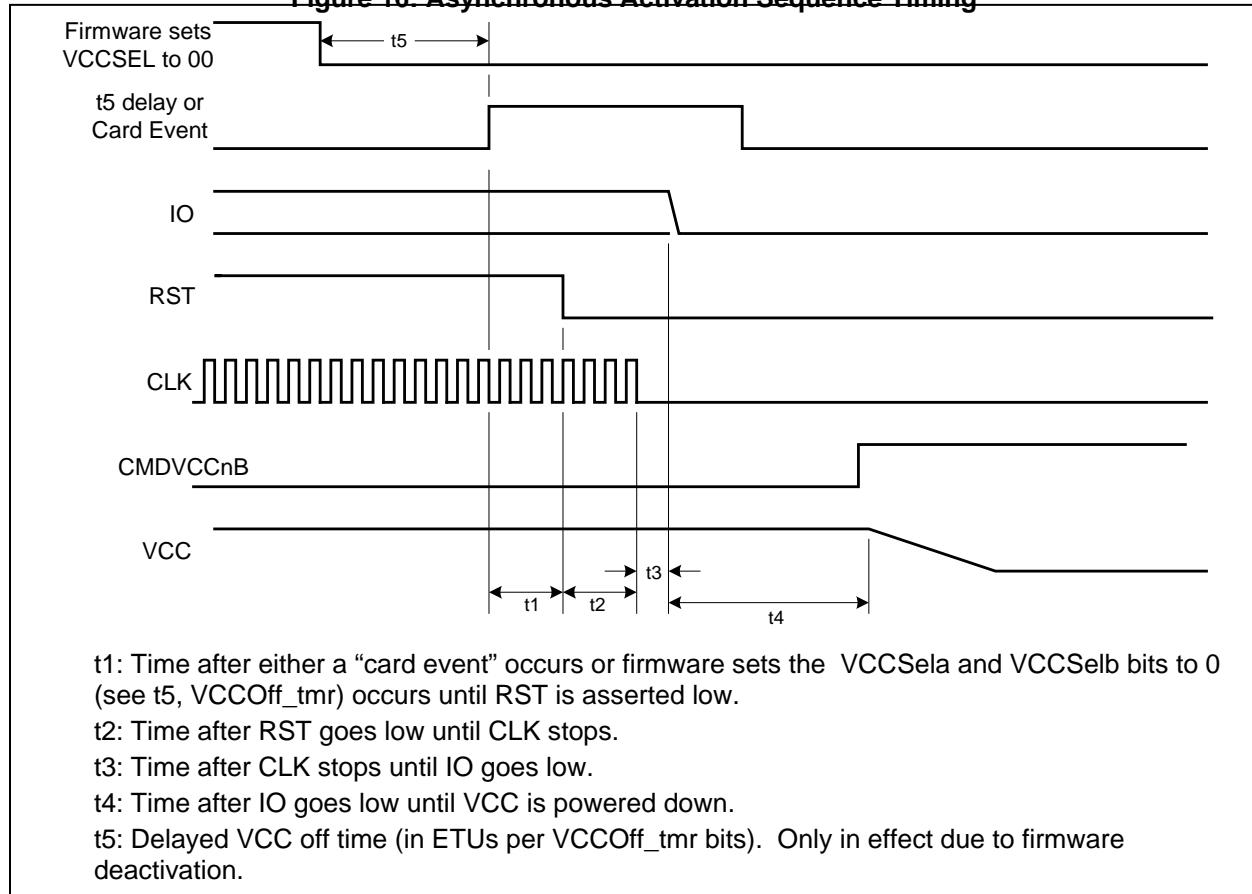


Figure 16: Asynchronous Activation Sequence Timing**Figure 17: Deactivation Sequence**

1.7.15.3 Data Reception/Transmission

When a 12Mhz crystal is used, the smart card UART will generate a 3.69Mhz (default) clock to both smart card interfaces. This will allow approximately 9600bps (1/ETU) communication during ATR (ISO 7816 default). As part of the PPS negotiation between the smart card and the reader, the firmware may determine that the smart card parameters F & D may be changed. After this negotiation, the firmware may change the ETU by writing to the SFR [FDReg](#) to adjust the ETU and CLK. The firmware may also change the smart card clock frequency by writing to the SFR [SCCLK](#) ([SCECLK](#) for external interface). Independent clock frequency control is provided to each smart card interface. Clock stop high or Clock stop low is supported in asynchronous mode. [Figure 18](#) shows the ETU and CLK control circuits. The firmware determines when clock stop is supported by the smart card and when it is appropriate to go into that mode (and when to come out of it). The smart card UART is clocked by the same clock that is provided to the selected smart card. The transition between smart card clocks is handled in hardware to eliminate any glitches for the UART during switchover. The external smart card clock is not affected when switching the UART to communicate with the internal smart card.

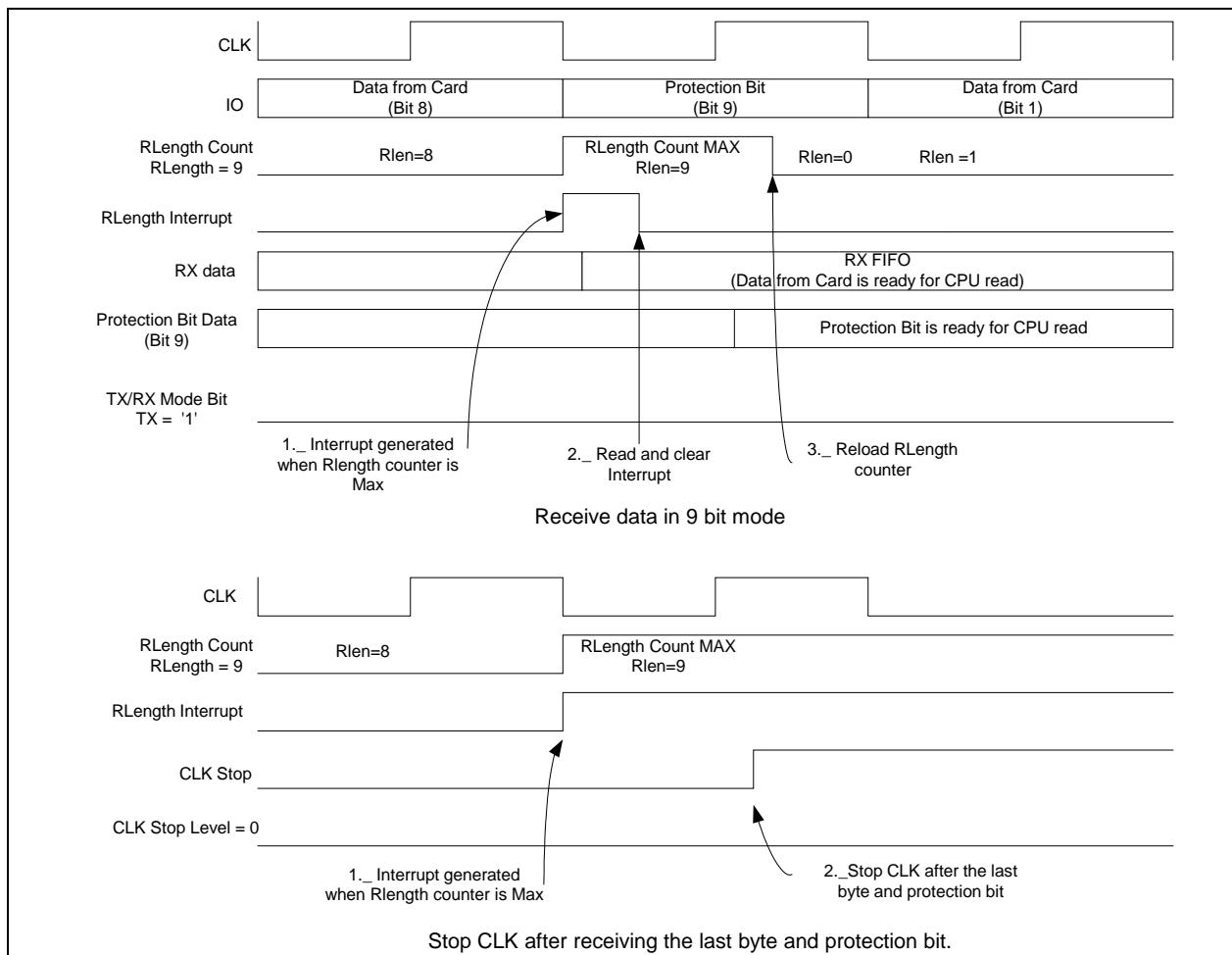


Figure 24: Operation of 9-bit Mode in Sync Mode

Synchronous card operation is broken down into three primary types. These are commonly referred to as 2-wire, 3-wire and I2C synchronous cards. Each card type requires different control and timing and therefore requires different algorithms to access. Teridian has created an application note to provide detailed algorithms for each card type. Refer to the application note titled “73S12xxF Synchronous Card Design Application Note”.

SRX Data Register (SRXData): 0xFE09 ← 0x00**Table 81: The SRXData Register**

MSB

LSB

SRXDAT.7	SRXDAT.6	SRXDAT.5	SRXDAT.4	SRXDAT.3	SRXDAT.2	SRXDAT.1	SRXDAT.0
----------	----------	----------	----------	----------	----------	----------	----------

Bit	Function
SRXData.7	
SRXData.6	
SRXData.5	
SRXData.4	(Read only) Data received from the smart card. Data received from the smart card gets stored in a FIFO that is read by the firmware.
SRXData.3	
SRXData.2	
SRXData.1	
SRXData.0	

Protocol Mode Register (SPrtcol): 0xFE0D ← 0x03

This register determines the protocol to be used when communicating with the selected smart card. This register should be updated as required when switching between smart card interfaces.

Table 85: The SPrtcol Register

MSB	LSB						
SCISYN	MOD9/8B	SCESYN	0	TMODE	CRCEN	CRCMS	RCVATR

Bit	Symbol	Function
SPrtcol.7	SCISYN	Smart Card Internal Synchronous mode - Configures internal smart card interface for synchronous mode. This mode routes the internal interface buffers for RST, IO, C4, C8 to the SCCtl register bits for direct firmware control. CLK is generated by the ETU counter.
SPrtcol.6	MOD9/8B	Synchronous 8/9 bit mode select - For sync mode, in protocols with 9-bit words, set this bit. The first eight bits read go into the RX FIFO and the ninth bit read will be stored in the IO (or SIO) data bit of the SRXCtl register.
SPrtcol.5	SCESYN	Smart Card External Synchronous mode - Configures External Smart Card interface for synchronous mode. This mode routes the external smart card interface buffers for SIO to SCECtl register bits for direct firmware control. SCLK is generated by the ETU counter.
SPrtcol.4	0	Reserved bit, must always be set to 0.
SPrtcol.3	TMODE	Protocol mode select - 0: T=0, 1: T=1. Determines which smart card protocol is to be used during message processing.
SPrtcol.2	CRCEN	CRC Enable – 1 = Enabled, 0 = Disabled. Enables the checking/generation of CRC/LRC while in T=1 mode. Has no effect in T=0 mode. If enabled and a message is being transmitted to the smart card, the CRC/LRC will be inserted into the message stream after the last TX byte is transmitted to the smart card. If enabled, CRC/LRC will be checked on incoming messages and the value made available to the firmware via the CRC LS/MS registers.
SPrtcol.1	CRCMS	CRC Mode Select – 1 = CRC, 0 = LRC. Determines type of checking algorithm to be used.
SPrtcol.0	RCVATR	Receive ATR – 1 = Enable ATR timeout, 0 = Disable ATR timeout. Set by firmware after the smart card has been turned on and the hardware is expecting ATR.

Block Guard Time Register (BGT): 0xFE16 ← 0x10

This register contains the Extra Guard Time Value (EGT) most-significant bit. The Extra Guard Time indicates the minimum time between the leading edges of the start bit of consecutive characters. The delay depends on the T=0/T=1 mode. Used in transmit mode. This register also contains the Block Guard Time (BGT) value. Block Guard Time is the minimum time between the leading edge of the start bit of the last character received and the leading edge of the start bit of the first character transmitted. This should not be set less than the character length. The transmission of the first character will be held off until BGT has elapsed regardless of the TX data and TX/RX control bit timing.

Table 95: The BGT Register

MSB	LSB							
EGT.8	-	-	BGT.4	BGT.3	BGT.1	BGT.2	BGT.0	

Bit	Symbol	Function
BGT.7	EGT.8	Most-significant bit for 9-bit EGT timer. See the EGT register.
BGT.6	-	
BGT.5	-	
BGT.4	BGT.4	
BGT.3	BGT.3	
BGT.2	BGT.2	
BGT.1	BGT.1	
BGT.0	BGT.0	

Extra Guard Time Register (EGT): 0xFE17 ← 0x0C

This register contains the Extra Guard Time Value (EGT) least-significant byte. The Extra Guard Time indicates the minimum time between the leading edges of the start bit of consecutive characters. The delay depends on the T=0/T=1 mode. Used in transmit mode.

Table 96: The EGT Register

MSB	LSB							
EGT.7	EGT.6	EGT.5	EGT.4	EGT.3	EGT.1	EGT.2	EGT.0	

Bit	Function
EGT.7	
EGT.6	
EGT.5	Time in ETUs between start bits of consecutive characters. In T=0 mode, the minimum is 1. In T=0, the leading edge of the next start bit may be delayed if there is a break detected from the smart card.
EGT.4	Default value is 12. In T=0 mode, regardless of the value loaded, the minimum value is 12, and for T=1 mode, the minimum value is 11.
EGT.3	
EGT.2	
EGT.1	
EGT.0	

Shaded locations indicate functions that are not provided in the synchronous mode.

Table 107: Smart Card SFR Table

Name	Address	b7	b6	b5	b4	b3	b2	b1	b0				
SCSel	FE00					SelSC(1:0)		BYPASS					
SCInt	FE01	WAITTO/ RLIEN	CRDEVT	VCCTMR	RXDAVI	TXEVNT	TXSENT	TXERR	RXERR				
SCIE	FE02	WTOI/ RLIEN	CDEVNT	VTMREN	RXDAEN	TXEVEN	TXSNTEN	TXERR	RXERR				
VccCtl	FE03	VCCSEL.1	VCCSEL.0	VDDFLT	RDYST	VCCOK			SCPWRDN				
VCCTmr	FE04		OFFTMR(3:0)			VCCTMR(3:0)							
CRDCtl	FE05	DEBOUN	CDETEN			DETPOL	PUENB	PDEN	CARDIN				
STXCtl	FE06	I2CMODE		TXFULL	TXEMTY	TXUNDL	LASTTX	TX/RXB	BREAKD				
STXData	FE07			TXDATA(7:0)									
SRXCtl	FE08	BIT9DAT		LASTRX	CRCERR	RXFULL	RXEMTY	RXOVRR	PARITYE				
SRXData	FE09			RXDATA(7:0)									
SCCtl	FE0A	RSTCRD		IO	IOD	C8	C4	CLKLVL	CLKOFF				
SCECtl	FE0B			SIO	SIOD			SCLKLVL	SCLKOFF				
SCDIR	FE0C					C8D	C4D						
SPrtcol	FE0D	SCISYN	MOD9/8B	SCESYN	0	TMODE	CRCEN	CRCMS	RCVATR				
SCCLK	FE0F			ICLKFS(5:0)									
SCECLK	FE10			ECLKFS(5:0)									
SParCtl	FE11		DISPAR	BRKGEN	BRKDET	RTRAN	DISCRX	INSPE	FORCPE				
SByteCtl	FE12		DETTS	DIRTS	BRKDUR (1:0)								
FDReg	FE13		FVAL(3:0)			DVAL (3:0)							
CRCMsB	FE14			CRC(15:8)									
CRCLsB	FE15			CRC(7:0)									
BGT	FE16	EGT8					BGT(4:0)						
EGT	FE17			EGT(7:0)									
BWTB3	FE18						BWT(27:24)						
BWTB2	FE19			BWT(23:16)									
BWTB1	FE1A			BWT(15:8)									
BWTB0	FE1B			BWT(7:0)									
CWTB1	FE1C			CWT(15:8)									
CWTB0	FE1D			CWT(7:0)									
ATRMsB	FE1F			ATRTO(15:8)									
ATRLsB	FE20			ATRTO(7:0)									
STSTO	FE21			TSTO(7:0)									
RLength	FE22			RLen(7:0)									

1.7.16 VDD Fault Detect Function

The 73S1210F contains a circuit to detect a low-voltage condition on the supply voltage V_{DD} . If enabled, it will deactivate the active internal smart card interface when V_{DD} falls below the V_{DD} Fault threshold. The register configures the V_{DD} Fault threshold for the nominal default of 2.3V* or a user selectable threshold. The user's code may load a different value using the FOVRVDDF bit = 1 after the power-up cycle has completed.

VDDFault Control Register (VDDFCtl): 0xFFD4 ← 0x00

Table 108: The VDDFCtl Register

MSB	LSB						
–	FOVRVDDF	VDDFLTEN	–	STXDAT.3	VDDFTH.2	VDDFTH.1	VDDFTH.0

Bit	Symbol	Function
VDDFCtl.7	–	
VDDFCtl.6	FOVRVDDF	Setting this bit high will allow the VDDFLT(2:0) bits set in this register to control the VDDFault threshold. When this bit is set low, the VDDFault threshold will be set to the factory default setting of 2.3V*.
VDDFCtl.5	VDDFLTEN	Set = 1 will disable VDD Fault operation.
VDDFCtl.4	–	
VDDFCtl.3	–	
VDDFCtl.2	VDDFTH.2	VDD Fault Threshold. Bit Value(2:0) VDDFault Voltage 000 2.3 (nominal default) 001 2.4 010 2.5 011 2.6 100 2.7 101 2.8 110 2.9 111 3.0
VDDFCtl.1	VDDFTH.1	
VDDFCtl.0	VDDFTH.0	

* Note: The V_{DD} Fault factory default can be set to any threshold as defined by bits VDDFTH(2:0). The 73S1210F has the capability to burn fuses at the factory to set the factory default to any of these voltages. Contact Teridian for further details.

2 Typical Application Schematic

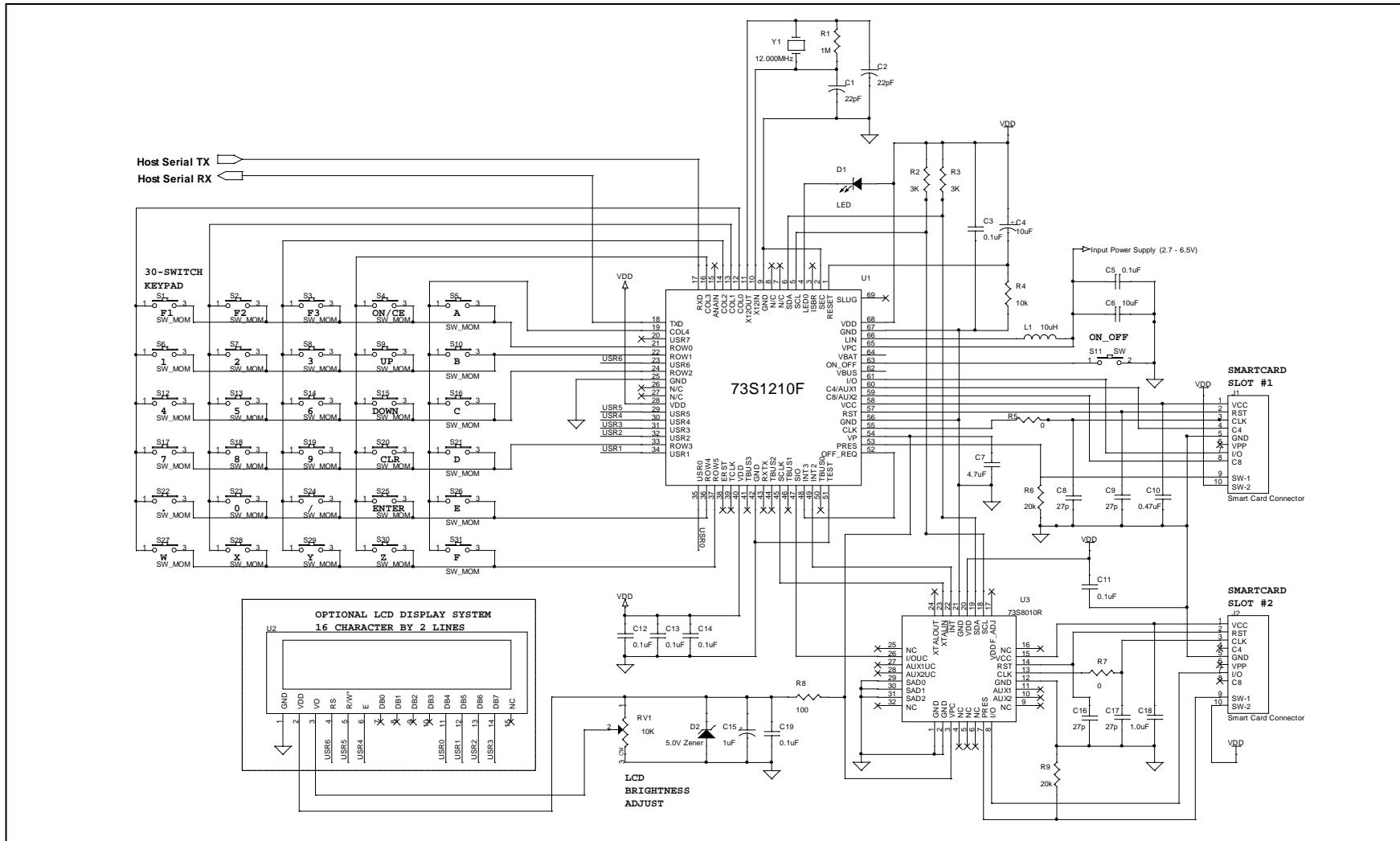


Figure 25: 73S1210F Typical Application Schematic

Symbol	Parameter	Condition	Min	Typ.	Max	Unit
Interface Requirements – Data Signals: I/O, AUX1 and AUX2						
V _{OH}	Output level, high	I _{OH} = 0	0.9 * V _{cc}		V _{cc} +0.1	V
		I _{OH} = -40μA	0.75 V _{cc}		V _{cc} +0.1	V
V _{OL}	Output level, low	I _{OL} = 1mA			0.15 *V _{cc}	V
V _{IH}	Input level, high		0.6 * V _{cc}		V _{cc} +0.30	V
V _{IL}	Input level, low		-0.15		0.2 * V _{cc}	V
V _{INACT}	Output voltage when outside of session	I _{OL} = 0			0.1	V
		I _{OL} = 1mA			0.3	V
I _{LEAK}	Input leakage	V _{IH} = V _{cc}			10	μA
I _{IL}	Input current, low	V _{IL} = 0			0.65	mA
I _{IL}	Input current, low	V _{IL} = 0			0.7	mA
I _{SHORTL}	Short circuit output current	For output low, shorted to V _{cc} through 33Ω			15	mA
I _{SHORTH}	Short circuit output current	For output high, shorted to ground through 33Ω			15	mA
t _R , t _F	Output rise time, fall times	For I/O, AUX1, AUX2, C _L = 80pF, 10% to 90%. For I/OUC, AUX1UC, AUX2UC, CL = 50pF, 10% to 90%.			100	ns
t _{IR} , t _{IF}	Input rise, fall times				1	μs
R _{PU}	Internal pull-up resistor	Output stable for >200ns	8	11	14	kΩ
FD _{MAX}	Maximum data rate				1	MHz
Reset and Clock for card interface, RST, CLK						
V _{OH}	Output level, high	I _{OH} = -200μA	0.9 * V _{cc}		V _{cc}	V
V _{OL}	Output level, low	I _{OL} = 200μA	0		0.15 *V _{cc}	V
V _{INACT}	Output voltage when outside of session	I _{OL} = 0			0.1	V
		I _{OL} = 1mA			0.3	V
I _{RST_LIM}	Output current limit, RST				30	
I _{CLK_LIM}	Output current limit, CLK				70	mA
t _R , t _F	Output rise time, fall time	C _L = 35pF for CLK, 10% to 90%			8	ns
		C _L = 200pF for RST, 10% to 90%			100	ns
δ	Duty cycle for CLK	C _L = 35pF, F _{CLK} ≤ 20MHz, CLKIN duty cycle is 48% to 52%.	45		55	%